

SUBSTRATE PROCESSING METHOD, SUBSTRATE PROCESSING DEVICE, AND SUBSTRATE PROCESSING SYSTEM

ABSTRACT

5 A disclosed substrate processing method includes placing a
substrate on an electrostatic chuck of a substrate support of a substrate
processing apparatus. The electrostatic chuck includes a substrate
support surface. The substrate includes a back surface and an organic
layer formed in advance on the back surface. The substrate is placed on
the electrostatic chuck so that the organic layer is in contact with the
10 substrate support surface. The substrate processing method further
includes holding the substrate by electrostatic attraction using the
electrostatic chuck. The substrate processing method further includes
processing the substrate in the substrate processing apparatus.

Fig. 5